#### CMLM0205

# **MULTI DISCRETE MODULE**™

SURFACE MOUNT SILICON N-CHANNEL MOSFET AND LOW V<sub>F</sub> SCHOTTKY DIODE



SOT-563 CASE



www.centralsemi.com

# **DESCRIPTION:**

The CENTRAL SEMICONDUCTOR CMLM0205 is a Multi Discrete Module  $^{\text{TM}}$  consisting of a single N-Channel MOSFET and a low  $V_F$  Schottky diode packaged in a space saving SOT-563 case. This device is designed for small signal general purpose applications where size and operational efficiency are prime requirements.

• Combination: N-Channel MOSFET and Low V<sub>F</sub> Schottky Diode.

**MARKING CODE: C25** 

		MARRING	ODL. 023	
MAXIMUM RAT	INGS - CASE: (T <sub>A</sub> =25°C)	SYMBOL		UNITS
Power Dissipation	n	$P_{D}$	350	mW
Operating and Storage Junction Temperature		T <sub>J</sub> , T <sub>stg</sub>	-65 to +150	°C
Thermal Resistance		$\Theta_{JA}$	357	°C/W
MAXIMUM RATINGS - Q1: (T <sub>A</sub> =25°C)		SYMBOL		UNITS
Drain-Source Voltage		$V_{DS}$	60	V
Drain-Gate Voltage		$V_{DG}$	60	V
Gate-Source Voltage		V <sub>GS</sub>	40	V
Continuous Drain Current		ID	280	mA
Continuous Source Current (Body Diode)		IS	280	mA
Maximum Pulsed Drain Current		I <sub>DM</sub>	1.5	Α
Maximum Pulsed Source Current		I <sub>SM</sub>	1.5	Α
MAXIMUM RATINGS - D1: (T <sub>A</sub> =25°C)		SYMBOL		UNITS
Peak Repetitive Reverse Voltage		VRRM	40	V
Continuous Forward Current		I <sub>F</sub>	500	mA
Peak Repetitive Forward Current, tp≤1.0ms		I <sub>FRM</sub>	3.5	Α
Peak Forward Surge Current, tp=8.0ms		I <sub>FSM</sub>	10	Α
ELECTRICAL C	HARACTERISTICS - Q1: (T <sub>A</sub> =2	5°C unless otherwi	se noted)	
SYMBOL	TEST CONDITIONS	MIN	MAX	UNITS
IGSSF, IGSSR	V <sub>GS</sub> =20V, V <sub>DS</sub> =0		100	nA
I <sub>DSS</sub>	V <sub>DS</sub> =60V, V <sub>GS</sub> =0		1.0	μΑ
IDSS	V <sub>DS</sub> =60V, V <sub>GS</sub> =0, T <sub>J</sub> =125°C		500	μA
I <sub>D</sub> (ON)	V <sub>GS</sub> =10V, V <sub>DS</sub> =10V	500		mA
BVDSS	$V_{GS}=0$ , $I_D=10\mu A$	60		V
V <sub>GS(th)</sub>	$V_{DS}=V_{GS}$ , $I_{D}=250\mu A$	1.0	2.5	V
V <sub>DS</sub> (ON)	$V_{GS}$ =10V, $I_D$ =500mA		1.0	V
V <sub>DS</sub> (ON)	$V_{GS}$ =5.0V, $I_D$ =50mA		0.15	V
V <sub>SD</sub>	V <sub>GS</sub> =0, I <sub>S</sub> =400mA		1.2	V
rDS(ON)	$V_{GS}$ =10V, $I_D$ =500mA		2.0	Ω
rDS(ON)	V <sub>GS</sub> =10V, I <sub>D</sub> =500mA, T <sub>J</sub> =125°	°C	3.5	Ω

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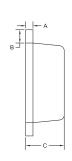
SURFACE MOUNT SILICON N-CHANNEL MOSFET AND LOW V<sub>F</sub> SCHOTTKY DIODE

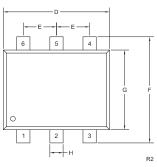


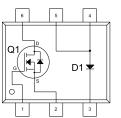
### **ELECTRICAL CHARACTERISTICS - Q1 - Continued:**

SYMBOL	TEST CONDITIONS	MIN	MAX	UNITS		
rDS(ON)	V <sub>GS</sub> =5.0V, I <sub>D</sub> =50mA		3.0	Ω		
rDS(ON)	$V_{GS}$ =5.0V, $I_D$ =50mA, $T_J$ =125°C		5.0	Ω		
9FS	V <sub>DS</sub> =10V, I <sub>D</sub> =200mA	80		mS		
C <sub>rss</sub>	$V_{DS}$ =25V, $V_{GS}$ =0, f=1.0MHz		5.0	pF		
C <sub>iss</sub>	$V_{DS}$ =25V, $V_{GS}$ =0, f=1.0MHz		50	pF		
C <sub>oss</sub>	$V_{DS}$ =25V, $V_{GS}$ =0, f=1.0MHz		25	pF		
t <sub>on</sub> / t <sub>off</sub>	$V_{DD}$ =30V, $V_{GS}$ =10V, $I_{D}$ =200mA					
	$R_G=25\Omega$ , $R_L=150\Omega$		20	ns		
ELECTRICAL CHARACTERISTICS - D1: (T <sub>A</sub> =25°C)						
$I_{R}$	V <sub>R</sub> =10V		20	μΑ		
$I_{R}$	V <sub>R</sub> =30V		100	μΑ		
$BV_R$	I <sub>R</sub> =500μA	40		V		
$V_{F}$	I <sub>F</sub> =100μA		0.13	V		
$V_{F}$	I <sub>F</sub> =1.0mA		0.21	V		
$V_{F}$	I <sub>F</sub> =10mA		0.27	V		
$V_{F}$	I <sub>F</sub> =100mA		0.35	V		
$V_{F}$	I <sub>F</sub> =500mA		0.47	V		
CJ	V <sub>R</sub> =1.0V, f=1.0MHz		50	pF		

### **SOT-563 CASE - MECHANICAL OUTLINE**







DIMENSIONS								
	INCHES		MILLIMETERS					
SYMBOL	MIN	MAX	MIN	MAX				
Α	0.0027	0.007	0.07	0.18				
В	0.008		0.20					
С	0.017	0.024	0.45	0.60				
D	0.059	0.067	1.50	1.70				
E	0.020		0.50					
F	0.059	0.067	1.50	1.70				
G	0.043	0.051	1.10	1.30				
Н	0.006	0.012	0.15	0.30				
SOT-563 (REV: R2)								

# LEAD CODE:

- 1) Gate Q1
- 2) Source Q1
- 3) Cathode D1
- 4) Anode D1
- 5) Anode D1
- 6) Drain Q1

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R3 (15-June 2015)

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R3 (15-June 2015)